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Very Low Forward Voltage Trench-based Schottky Rectifier

Features

- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb–Free and Halide–Free Devices

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 11.7 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

Typical Applications

 Switching Power Supplies including Compact Adapters and Flat Panel Display

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- High Frequency and DC–DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation
- Automotive LED Lighting



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TRENCH SCHOTTKY RECTIFIER 2.0 AMPERES 45 VOLTS



SOD-123FL CASE 498 PLASTIC

MARKING DIAGRAM



2AE = Specific Device Code

M = Date Code

■ = Pb-Free Package (Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|----------------------|------------------------|
| NRVTS245ESFT1G | SOD-123 (Pb-Free) | 3,000/ Tape & Reel |
| NRVTS245ESFT3G | SOD-123 (Pb-Free) | 10,000/ Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|--|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 45 | V |
| Average Rectified Forward Current (T _L = 148°C) | lo | 2.0 | А |
| Peak Repetitive Forward Current (Square Wave, 20 kHz, T _L = 143°C) | I _{FRM} | 4.0 | Α |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I _{FSM} | 50 | А |
| Storage and Operating Junction Temperature Range (Note 1) | T _{stg} , T _J | -65 to +175 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|------------------|-------|------|
| Thermal Resistance, Junction-to-Lead (Note 2) | $\Psi_{\sf JCL}$ | 23 | °C/W |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 85 | °C/W |
| Thermal Resistance, Junction-to-Ambient (Note 3) | $R_{	heta JA}$ | 330 | °C/W |

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|----------------|--------------|----------|
| Maximum Instantaneous Forward Voltage (Note 4) $(I_F = 2.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(I_F = 2.0 \text{ A}, T_J = 125^{\circ}\text{C})$ | V _F | 0.65 0.58 | V |
| Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$) | I _R | 75 3 | μA mA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 2. Mounted with 700 mm² copper pad size (Approximately 1 in²) 1 oz FR4 Board.
- Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board.
 Pulse Test: Pulse Width ≤ 380 μs, Duty Cycle ≤ 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

TYPICAL CHARACTERISTICS

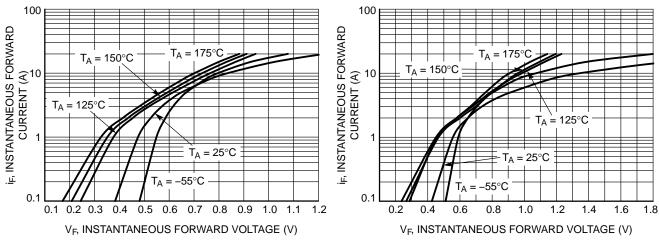


Figure 1. Typical Instantaneous Forward Characteristics

Figure 2. Maximum Instantaneous Forward Characteristics

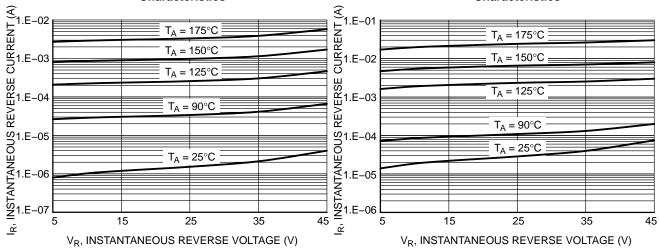


Figure 3. Typical Reverse Characteristics

Figure 4. Maximum Reverse Characteristics

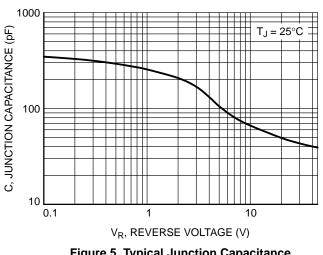


Figure 5. Typical Junction Capacitance

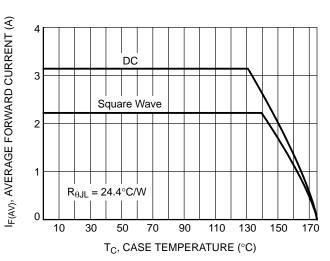
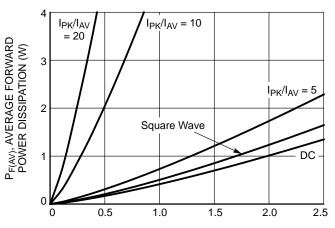


Figure 6. Current Derating

TYPICAL CHARACTERISTICS



I_{F(AV)}, AVERAGE FORWARD CURRENT (A)

Figure 7. Forward Power Dissipation

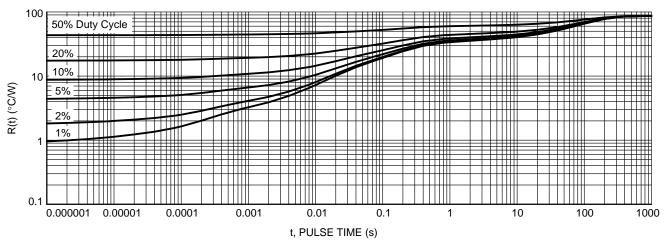
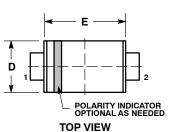


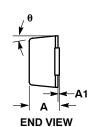
Figure 8. Thermal Characteristics

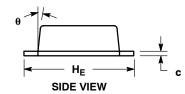


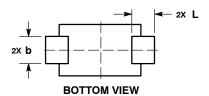
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DATE 10 MAY 2013

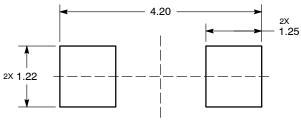








RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

NOTES:

- ES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
 DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION
 OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.90 | 0.95 | 0.98 | 0.035 | 0.037 | 0.039 |
| A1 | 0.00 | 0.05 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.70 | 0.90 | 1.10 | 0.028 | 0.035 | 0.043 |
| С | 0.10 | 0.15 | 0.20 | 0.004 | 0.006 | 0.008 |
| D | 1.50 | 1.65 | 1.80 | 0.059 | 0.065 | 0.071 |
| E | 2.50 | 2.70 | 2.90 | 0.098 | 0.106 | 0.114 |
| L | 0.55 | 0.75 | 0.95 | 0.022 | 0.030 | 0.037 |
| HE | 3.40 | 3.60 | 3.80 | 0.134 | 0.142 | 0.150 |
| θ | 0° | - | 8° | 0° | - | 8° |

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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|------------------|-------------|---|-------------|--|
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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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